

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3122557

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SEJE TAKAKI	11/21/2014
YOSHIO MORI	11/21/2014
RECEIVING PARTY DATA	
Name:	SANDISK 3D LLC
Street Address:	951 SANDISK DRIVE
City:	MILPITAS
State/Country:	CALIFORNIA
Postal Code:	95035
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14542213
CORRESPONDENCE DATA	
Fax Number:	(415)489-4150
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	415-489-4100
Email:	lmiller@vierramagen.com
Correspondent Name:	VIERRA MAGEN MARCUS LLP
Address Line 1:	575 MARKET STREET, SUITE 3750
Address Line 4:	SAN FRANCISCO, CALIFORNIA 94105
ATTORNEY DOCKET NUMBER:	SAND-01767US0
NAME OF SUBMITTER:	JAMES TROSINO
SIGNATURE:	/James Trosino/
DATE SIGNED:	11/25/2014
Total Attachments: 3	
source=1767-exec-assignment#page1.tif	
source=1767-exec-assignment#page2.tif	
source=1767-exec-assignment#page3.tif	

JOINT TO CORPORATE ASSIGNMENT

WHEREAS, the undersigned Inventors:

(1) Seje Takaki, a resident of Yokkaichi, Japan; and

(2) Yoshio Mori, a resident of Yokkaichi, Japan,

have invented certain new and useful improvements in:

MONOLITHIC THREE DIMENSIONAL MEMORY ARRAYS WITH STAGGERED VERTICAL BIT LINE SELECT TRANSISTORS AND METHODS THEREFOR

and have executed a declaration for an application for a United States Patent disclosing and identifying the invention, said application having Application Number 14/542,213 and filed on the 14th day of November, 2014.

WHEREAS SanDisk 3D, LLC (hereinafter termed "Assignee"), a corporation of the State of Delaware, having a place of business at 951 SanDisk Drive, Milpitas, State of California, wishes to acquire the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey to said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein

conveyed in the United States and other countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting applications for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.

4. Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

Date: 11 21, 2014

(1) Seje Takaki
Seje Takaki

Date: 11. 21. 2014

(2) Yoshio Mori
Yoshio Mori